## CLAIMS

1. A factory interface for an electronic device manufacturing system, the factory interface comprising:

an interior volume defined by a bottom, a top and a plurality of sides, wherein the plurality of sides comprise a back side that is configured to face a transfer chamber of the electronic device manufacturing system, a right side and a left side;

a first load lock disposed within the interior volume of the factory interface, wherein the first load lock comprises a first door that is approximately perpendicular to the back side, and a second door that is approximately parallel to the back side and accessible by a transfer chamber robot;

a second load lock disposed within the interior volume of the factory interface, wherein the second load lock comprises a third door that is approximately perpendicular to the back side, and a fourth door that is approximately parallel to the back side and accessible by the transfer chamber robot, wherein the second load lock is adjoined to the first load lock;

a first factory interface robot disposed within the interior volume of the factory interface, wherein the first factory interface robot is configured to transfer substrates between a first set of substrate carriers and the first load lock, wherein the first load lock is accessible by the first factory interface robot; and

a second factory interface robot configured to transfer substrates between a second set of substrate carriers and the second load lock, wherein the second load lock is accessible by the second factory interface robot.

2. The factory interface of claim 1, wherein the first factory interface robot is disposed within the interior volume proximate to the left side, wherein the second factory interface robot is disposed within the interior volume proximate to the right side, and wherein the first load lock and the second load lock are disposed adjacent to the back side and between the first factory interface robot and the second factory interface robot such that the first load lock is nearer to the first factory interface robot than the second load lock and the second load lock is nearer to the second factory interface robot than the first load lock.

3. The factory interface of claim 2, further comprising:

a first set of load ports for receiving the first set of substrate carriers, wherein the first set of load ports are positioned at a first portion of a front side of the plurality of sides, wherein the first portion is proximate to the left side; and

a second set of load ports for receiving the second set of substrate carriers, wherein the second set of load ports are positioned at a second portion of the front side that is proximate to the right side.

4. The factory interface of claim 3, further comprising:

at least one of a substrate storage container or metrology equipment positioned below a load port of the first set of load ports.

5. The factory interface of claim 1, further comprising:

a via disposed within the interior volume of the factory interface above or below the first load lock, wherein the first factory interface robot is configured to transfer a substrate to the second factory interface robot through the via.

6. The factory interface of claim 1, wherein the first factory interface robot is disposed within the interior volume proximate to the left side, wherein the first load lock is disposed adjacent to the back side and between the first factory interface robot and the right side.

7. The factory interface of claim 1, wherein the first load lock is a batch load lock.

8. The factory interface of claim 1, wherein the second load lock disposed within the interior volume of the factory interface and below the first load lock.

9. The factory interface of claim 1, wherein the plurality of sides comprise a front side that comprises a center portion, a left front portion, and a right front portion, wherein the center portion protrudes away from the left front portion, the right front portion, and the back side, wherein a first load port for receiving a first substrate carrier from the first set of substrate carriers is positioned at a first position on the front left portion, and a second load port for receiving a second substrate carrier from the first set of substrate carries is positioned at a second position on the front right portion.

10. The factory interface of claim 9, further comprising:

a via disposed within the interior volume of the factory interface at the center portion that protrudes away from the left front portion, the right front portion, and the back side, wherein the first factory interface robot is configured to transfer a substrate to the second factory interface robot through the via.

11. An electronic device manufacturing system, comprising:

a transfer chamber;

a plurality of processing chambers connected to the transfer chamber;

a first load lock having a first side and a second side that is approximately perpendicular to the first side of the first load lock, wherein the first side of the first load lock is connected to the transfer chamber, wherein the first load lock comprises a first door that is approximately parallel to the first side and accessible by a transfer chamber robot, and a second door that is approximately parallel to the second side;

a second load lock having a third side and a fourth side that is approximately perpendicular to the third side of the second load lock, wherein the third side of the second load lock is connected to the transfer chamber, wherein the second load lock comprises a third door that is approximately parallel to the third side and accessible by the transfer chamber robot, and a fourth door that is approximately parallel to the fourth side, wherein the second load lock is adjoined to the first load lock;

a first factory interface connected to the second side of the first load lock; and

a second factory interface connected to the fourth side of the second load lock;

a first factory interface robot disposed within the interior volume of the first factory interface, wherein the first factory interface robot is configured to transfer substrates between a first set of substrate carriers and the first load lock; and

a second factory interface robot disposed within the interior volume of the second factory interface, wherein the second factory interface robot is configured to transfer substrates between a second set of substrate carriers and second first load lock.

12. The electronic device manufacturing system of claim 11, wherein the first factory interface comprises a first atmospheric environment and the second factory interface comprises a second atmospheric environment.

13. The electronic device manufacturing system of claim 11, wherein the first load lock and the second load lock are each a stacked load lock having a pair of upper interior chambers and a pair of lower interior chambers that are located at different vertical levels, wherein the electronic device manufacturing system further comprises:

a via disposed within between the pairs of upper interior chambers and the pairs of lower interior chambers, wherein the first factory interface robot is configured to transfer a substrate to the second factory interface robot through the via.

14. The electronic device manufacturing system of claim 11, wherein the first factory interface comprises a first set of load ports for receiving the first set of substrate carriers and the second factory interface comprises a second set of load ports.